

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: SAW FILTER
MODEL NO 型号: HDF333T F16
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ DATE 日期: 2006-5-11

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

This specification shall cover the characteristics of SAW filter F333T.

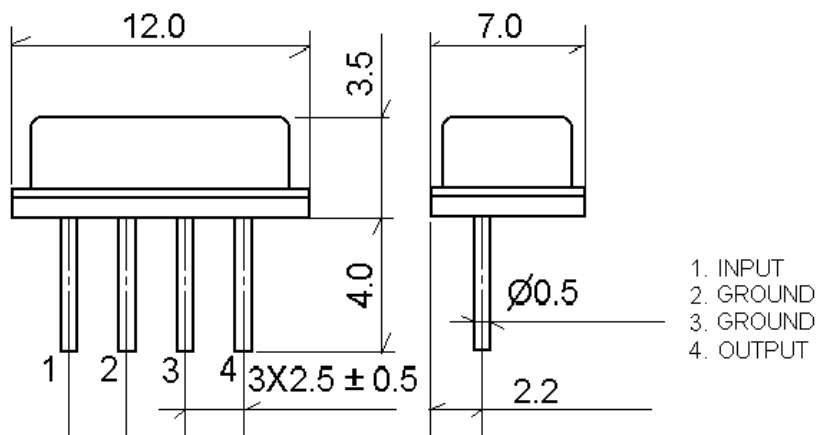
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

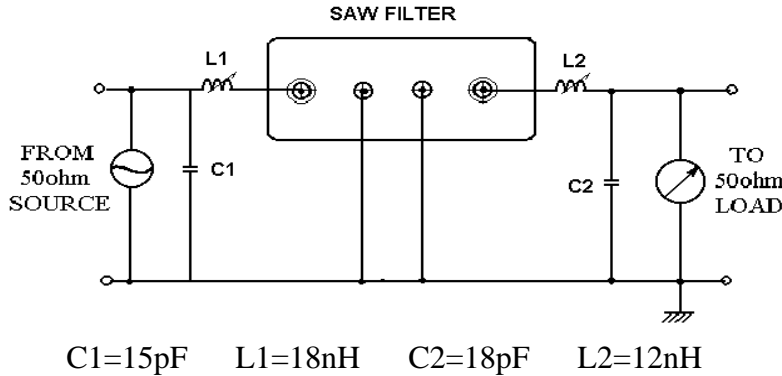
2.2 Electronic Characteristics

Item		Typ.value	Tolerance/Limit
Insertion Loss (reference level)	Ae=amin	8.0 dB	11.0 dB
Reference frequency	Fc(30dB-B W)	333.0 MHz	±120 kHz
Pass band shape(3 dB-BW)			Gaussian
3 dB bandwidth	BW	0.66 MHz	0.6MHz min
30 dB bandwidth		1.65 MHz	1.75MHz max
40 dB bandwidth		1.83 MHz	1.95MHz max
Group delay $f_c \pm 250\text{kHz}$ $f \pm 250\text{kHz}$	GD	400 ns	500 ns max 650 ns max
Triple Transit Suppression		31 dB	30 dB

3. DIMENSION



4. TEST CIRCUIT



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.